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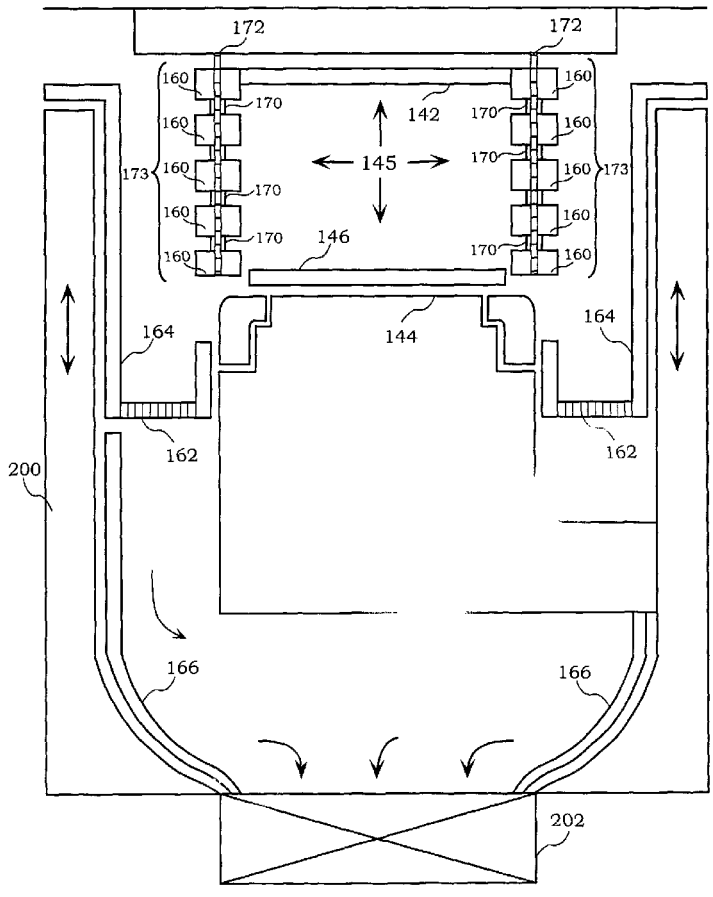
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(54) Title: CONFIGURABLE PLASMA VOLUME ETCH CHAMBER



(57) Abstract: A plasma processing chamber (200) is provided. The plasma processing chamber includes a bottom electrode (144) configured to support a substrate (146) and a top electrode (142) located over the bottom electrode. The plasma processing chamber further includes a plasma confinement assembly (173) designed to transition between a closed orientation and an open orientation. In the closed orientation, the plasma confinement assembly defines a first volume (145) for plasma during processing, and in the open orientation, the plasma confinement assembly defines a second volume during processing which is larger than the first volume.

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